SUBMINIATURE SOLID STATE LAMP

PRELIMINARY SPEC

Part Number: AM27SYCK09

Super Bright Yellow

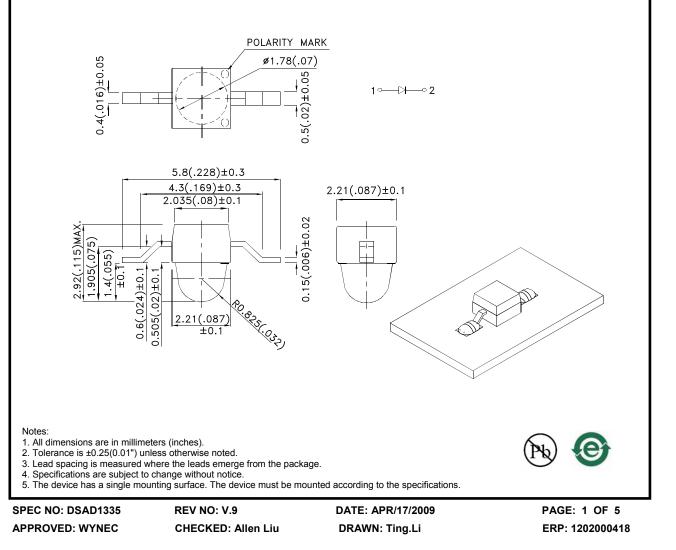
Features

- Subminiature package.
- Z-Bend lead.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM27SYCK09	Super Bright Yellow (AlGaInP)	WATER CLEAR	900	1800	20°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	IF=20mA
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Yellow		10	uA	VR=5V

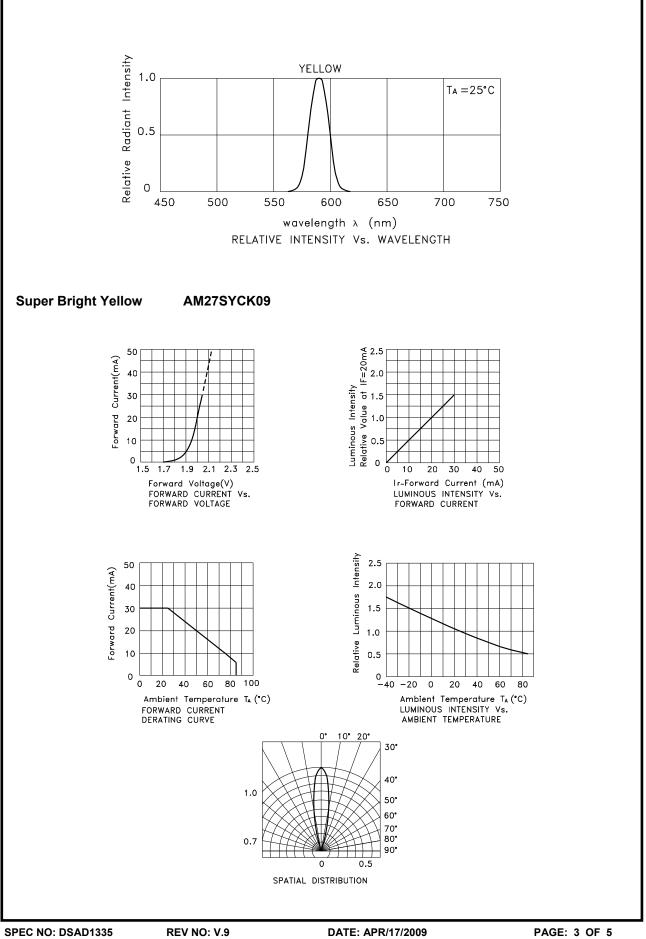
Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Yellow	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	175	mA	
Reverse Voltage	5	V	
Electrostatic Discharge Threshold (HBM)	3000	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	ge Temperature -40°C To +85°C		

Note:

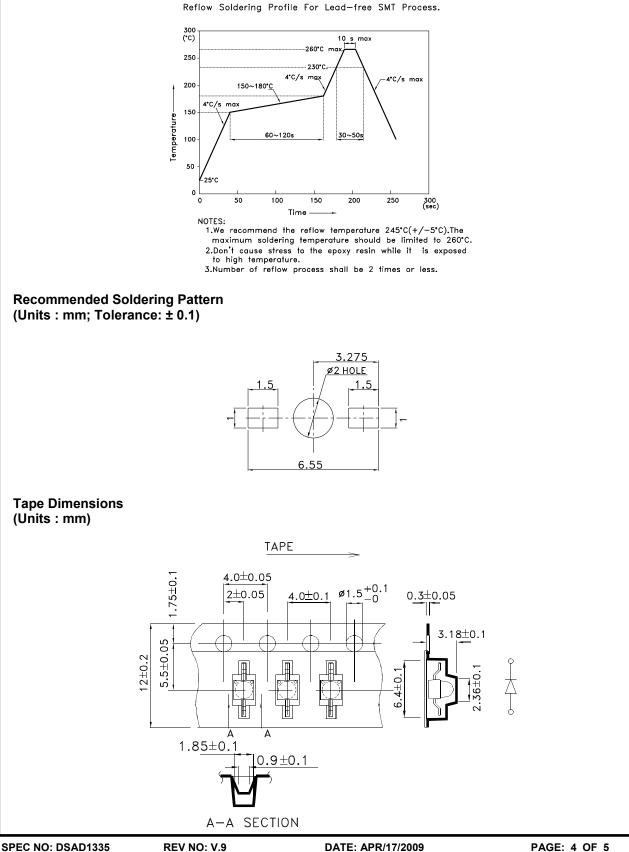
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



AM27SYCK09

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



CHECKED: Allen Liu

